[CLAIMS]

[Claim 1]

A manufacturing method of a mounting structure, the method comprising:

a step of preparing a mounting member including a first circuit member and a plurality of second circuit members placed on the first circuit member;

a step of preparing a sheet having thermosetting property;

a disposing step of disposing the sheet on the mounting member so as to face the second circuit members; and

a sealing step of pressing the sheet against the first circuit member and heating the sheet, to seal the second circuit members and to cure the sheet, wherein

the second circuit members include a reference member, and a first adjacent member and a second adjacent member each adjacent to the reference member,

a separation distance D1 between the reference member and the first adjacent member is different from a separation distance D2 between the reference member and the second adjacent member,

at least one of the plurality of the second circuit members is a hollow member to be provided with a space from the first circuit member,

the sheet includes a first layer being disposed on one outermost side and facing the second circuit members, and a second layer adjacent to the first layer,

the first layer being formed of a first resin composition containing a thermosetting resin,

the second layer being formed of a second resin composition containing a thermosetting resin,

a loss tangent tanδ at a temperature t when the second circuit members are sealed of the first resin composition is smaller than a loss tangent tanδ at the temperature t of the second resin composition, and

in the sealing step, the plurality of the second circuit members are sealed so as to maintain the space.

[Claim 2]

The manufacturing method of claim 1, wherein at least one of the first resin composition and the second resin composition has, at the temperature t, a loss tangent tanδ of 0.1 or more and 0.8 or less, and a storage shear modulus of 1×10^4 Pa or more and 1×10^7 Pa or less.

[Claim 3]

The manufacturing method of claim 2, wherein

the first resin composition and the second resin composition both have, at the temperature t, a loss tangent tanδ of 0.1 or more and 0.8 or less, and a storage shear modulus of 1×10^4 Pa or more and 1×10^7 Pa or less,

a layer formed of the first resin composition and having a thickness of 100 μm has an elongation percentage at the temperature t of 1000% or more, and

the first layer has a thickness of 50 μm or less.

[Claim 4]

The manufacturing method of claim 1, 2 or 3, wherein a height ΔH1 from the reference member of the first adjacent member is different from a height ΔH2 from the reference member of the second adjacent member.

[Claim 5]

A sheet for sealing a mounting member including a first circuit member and a plurality of second circuit members placed on the first circuit member, the sheet comprising:

a first layer being disposed on one outermost side and facing the second circuit members,

and a second layer adjacent to the first layer,

the first layer being formed of a first resin composition containing a thermosetting resin,

the second layer being formed of a second resin composition containing a thermosetting resin,

a loss tangent tanδ at a temperature t when the second circuit members are sealed of the first resin composition is smaller than a loss tangent tanδ at the temperature t of the second resin composition, wherein

the second circuit members include a reference member, and a first adjacent member and a second adjacent member each adjacent to the reference member,

a separation distance D1 between the reference member and the first adjacent member is different from a separation distance D2 between the reference member and the second adjacent member, and

at least one of the plurality of the second circuit members is a hollow member to be provided with a space from the first circuit member.

[Claim 6]

The sheet of claim 5, wherein at least one of the first resin composition and the second resin composition has, at the temperature t, a loss tangent tanδ of 0.1 or more and 0.8 or less, and a storage shear modulus of 1×10^4 Pa or more and 1×10^7 Pa or less.

[Claim 7]

The sheet of claim 6, wherein

the first resin composition and the second resin composition both have, at the temperature t, a loss tangent tanδ of 0.1 or more and 0.8 or less, and a storage shear modulus of 1×10^4 Pa or more and 1×10^7 Pa or less,

a layer formed of the first resin composition and having a thickness of 100 μm has an

elongation percentage at the temperature t of 1000% or more, and

the first layer has a thickness of 50 μm or less.

[Claim 8]

The sheet of any one of claims 5 to 7, wherein the second layer is entirely adjacent to the first layer.